FIG. 1

PRIOR ART

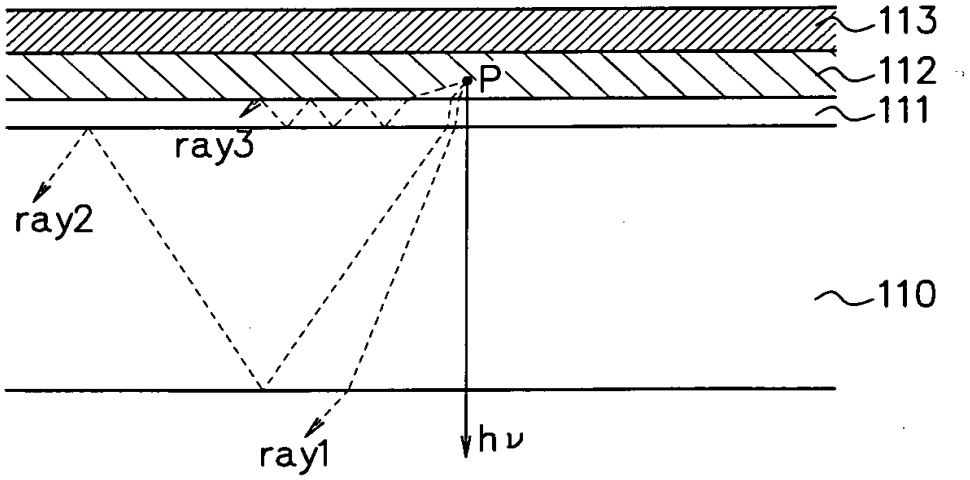


FIG. 2

PRIOR ART

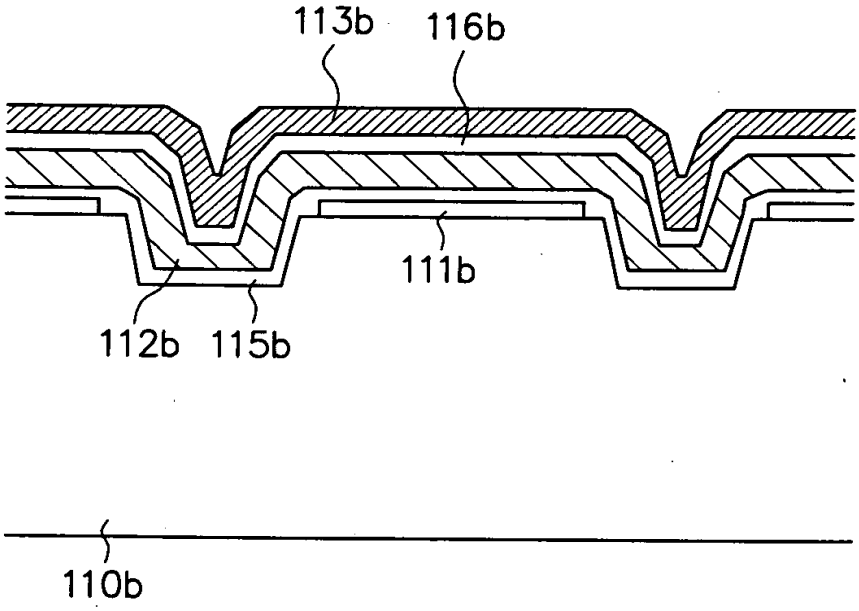


FIG. 3

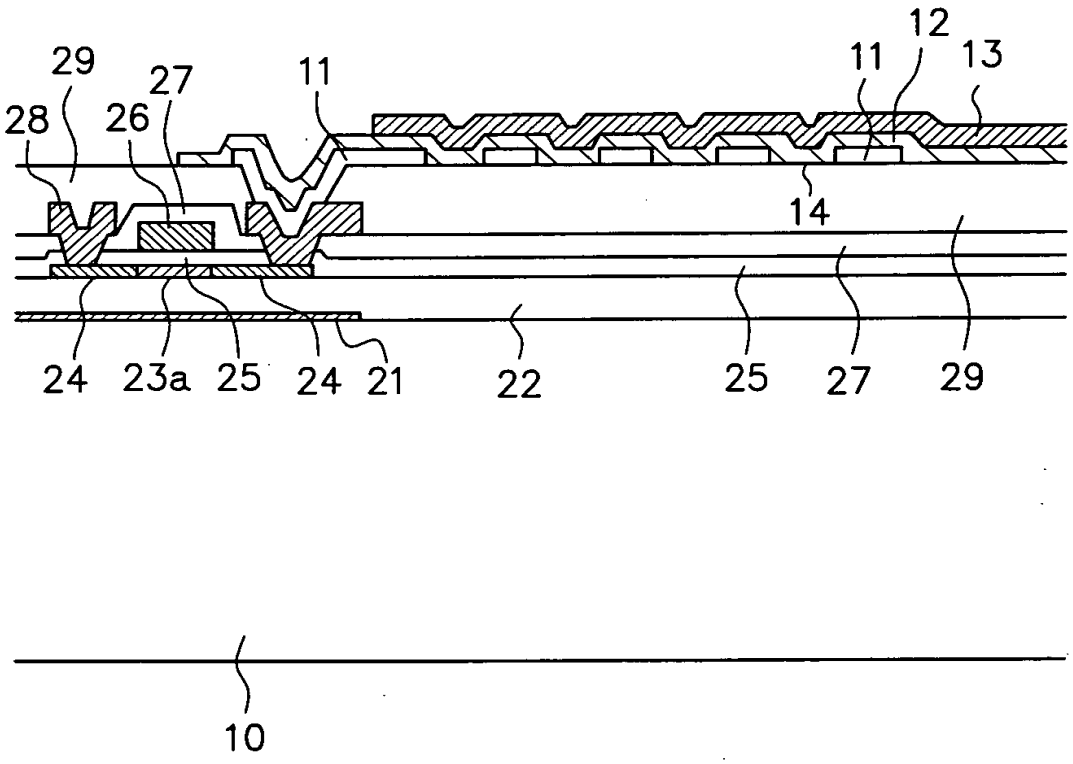


FIG. 4

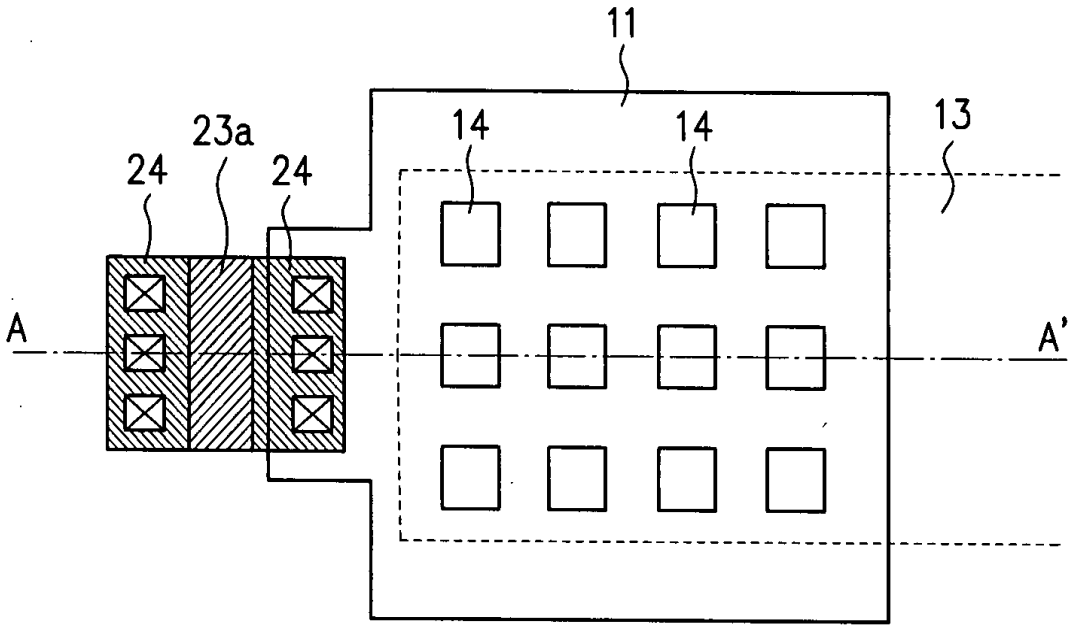


FIG. 5

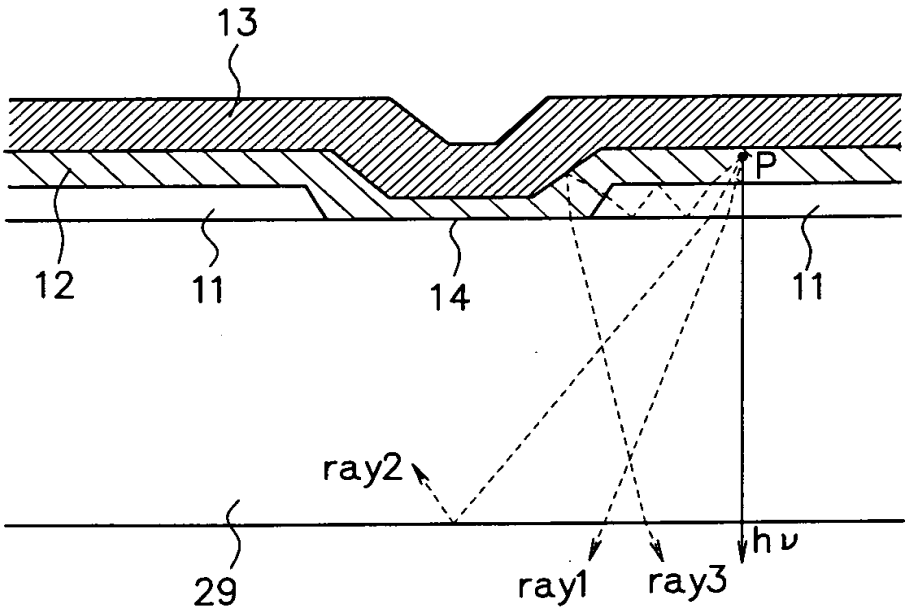


FIG. 6

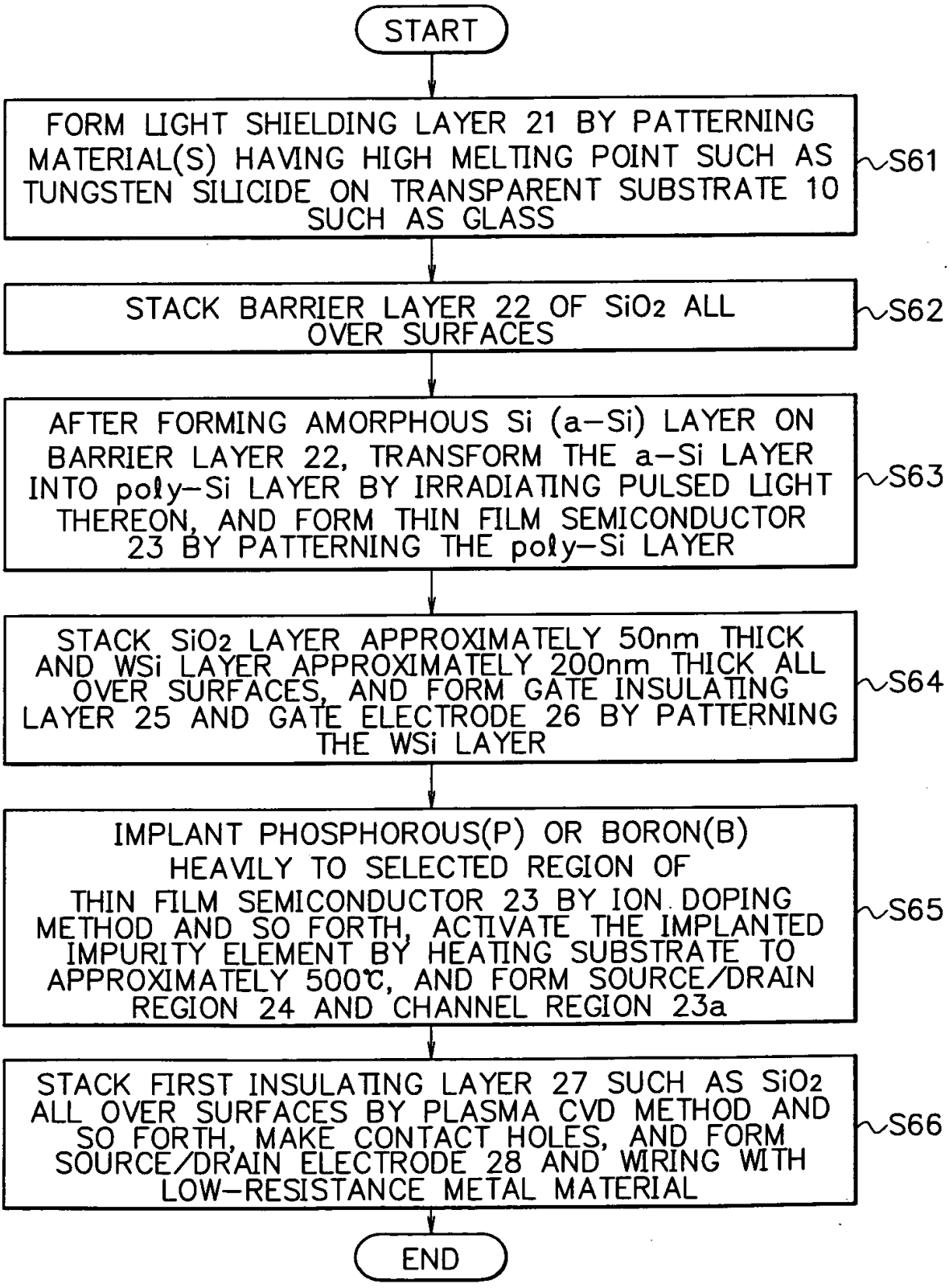

START
FORM LIGHT SHIELDING LAYER 21 BY PATTERNING MATERIAL(S) HAVING HIGH MELTING POINT SUCH AS TUNGSTEN SILICIDE ON TRANSPARENT SUBSTRATE 10 SUCH AS GLASS
S61
STACK BARRIER LAYER 22 OF SiO2 ALL OVER SURFACES
S62
AFTER FORMING AMORPHOUS Si (a-Si) LAYER ON BARRIER LAYER 22, TRANSFORM THE a-Si LAYER INTO poly-Si LAYER BY IRRADIATING PULSED LIGHT THEREON, AND FORM THIN FILM SEMICONDUCTOR 23 BY PATTERNING THE poly-Si LAYER
S63
STACK SiO2 LAYER APPROXIMATELY 50nm THICK AND WSi LAYER APPROXIMATELY 200nm THICK ALL OVER SURFACES, AND FORM GATE INSULATING LAYER 25 AND GATE ELECTRODE 26 BY PATTERNING THE WSi LAYER
S64
IMPLANT PHOSPHOROUS(P) OR BORON(B) HEAVILY TO SELECTED REGION OF THIN FILM SEMICONDUCTOR 23 BY ION DOPING METHOD AND SO FORTH, ACTIVATE THE IMPLANTED IMPURITY ELEMENT BY HEATING SUBSTRATE TO APPROXIMATELY 500℃, AND FORM SOURCE/DRAIN REGION 24 AND CHANNEL REGION 23a
S65
STACK FIRST INSULATING LAYER 27 SUCH AS SiO2 ALL OVER SURFACES BY PLASMA CVD METHOD AND SO FORTH, MAKE CONTACT HOLES, AND FORM SOURCE/DRAIN ELECTRODE 28 AND WIRING WITH LOW-RESISTANCE METAL MATERIAL
S66
END

FIG. 7

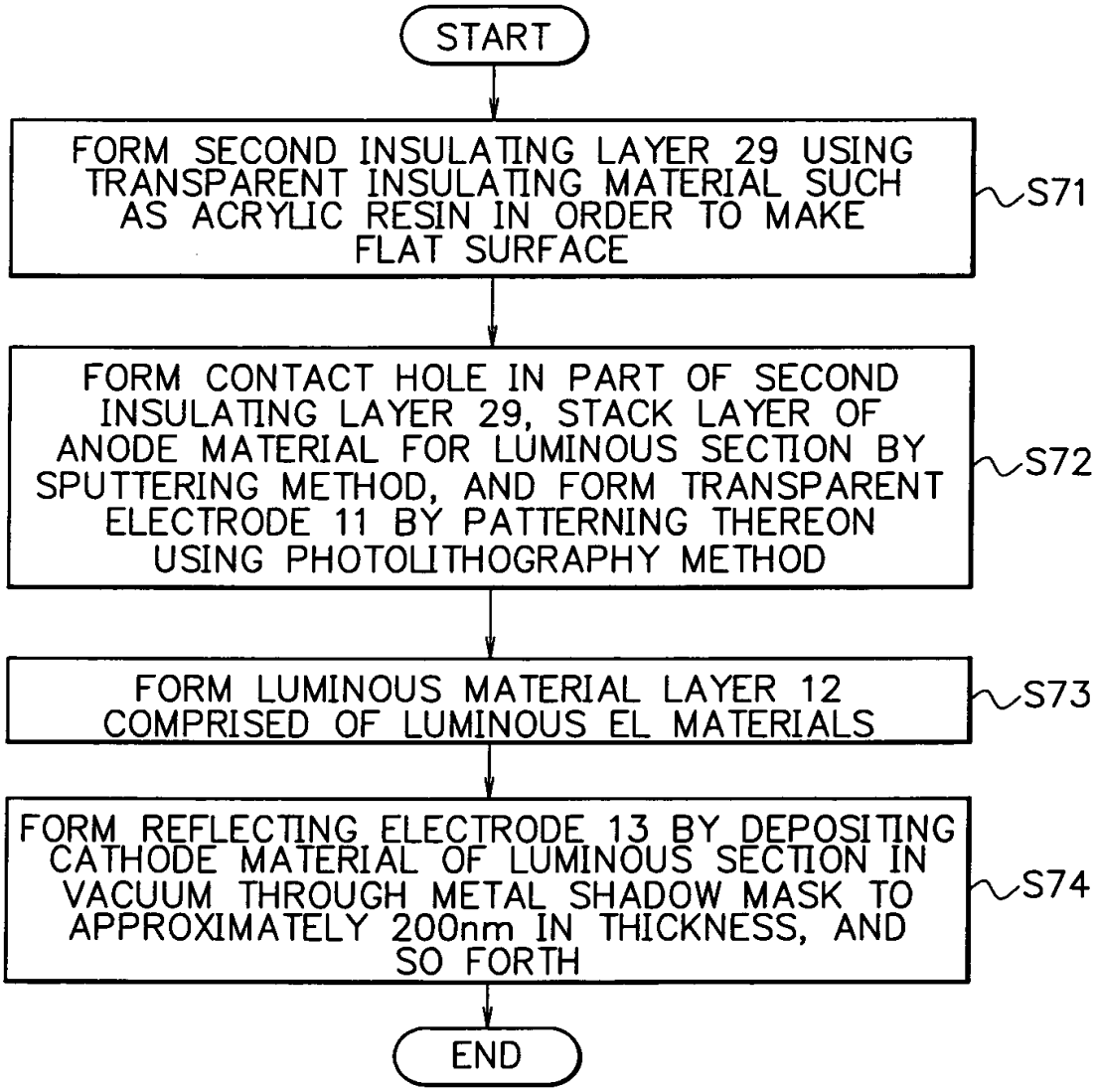

START
FORM SECOND INSULATING LAYER 29 USING TRANSPARENT INSULATING MATERIAL SUCH AS ACRYLIC RESIN IN ORDER TO MAKE FLAT SURFACE
S71
FORM CONTACT HOLE IN PART OF SECOND INSULATING LAYER 29, STACK LAYER OF ANODE MATERIAL FOR LUMINOUS SECTION BY SPUTTERING METHOD, AND FORM TRANSPARENT ELECTRODE 11 BY PATTERNING THEREON USING PHOTOLITHOGRAPHY METHOD
S72
FORM LUMINOUS MATERIAL LAYER 12 COMPRISED OF LUMINOUS EL MATERIALS
S73
FORM REFLECTING ELECTRODE 13 BY DEPOSITING CATHODE MATERIAL OF LUMINOUS SECTION IN VACUUM THROUGH METAL SHADOW MASK TO APPROXIMATELY 200nm IN THICKNESS, AND SO FORTH
S74
END

FIG. 8A

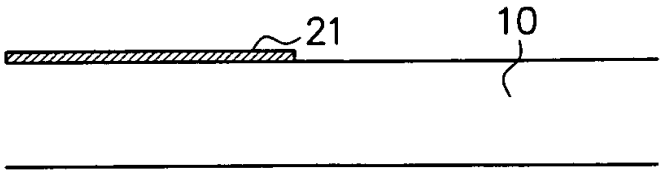


FIG. 8B

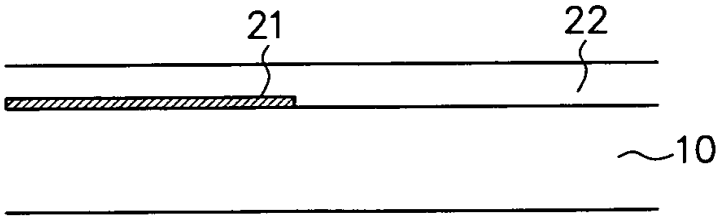


FIG. 8C

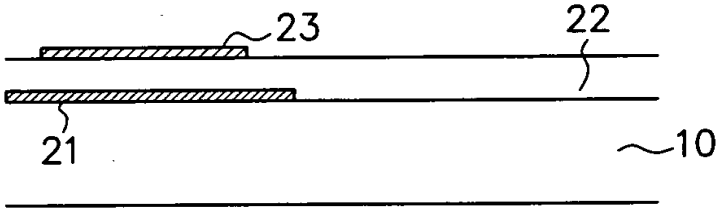


FIG. 8D

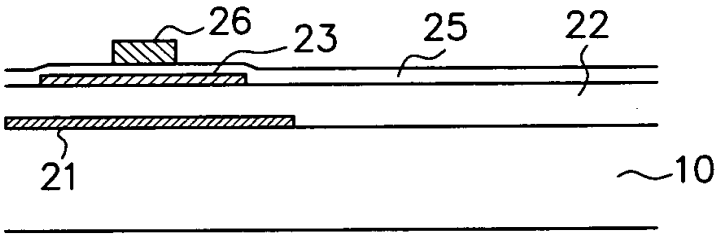


FIG. 8E

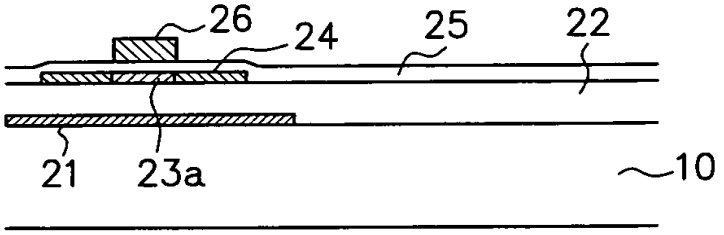


FIG. 8F

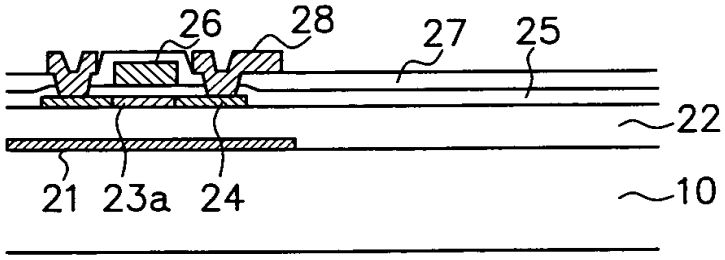


FIG. 9A

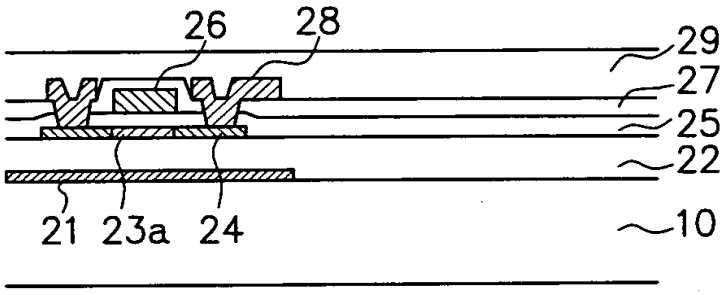


FIG. 9B

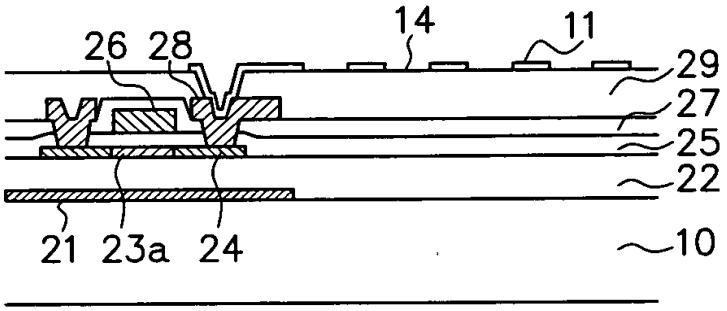


FIG. 9C

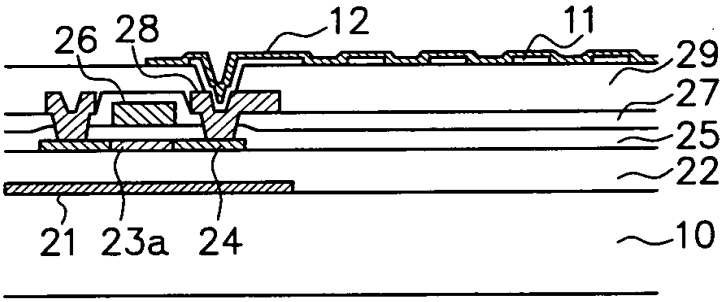


FIG. 9D

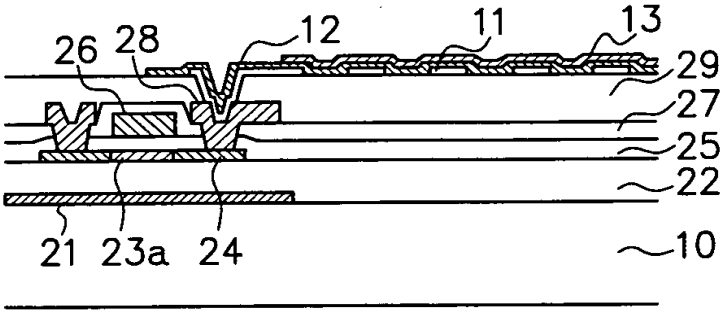
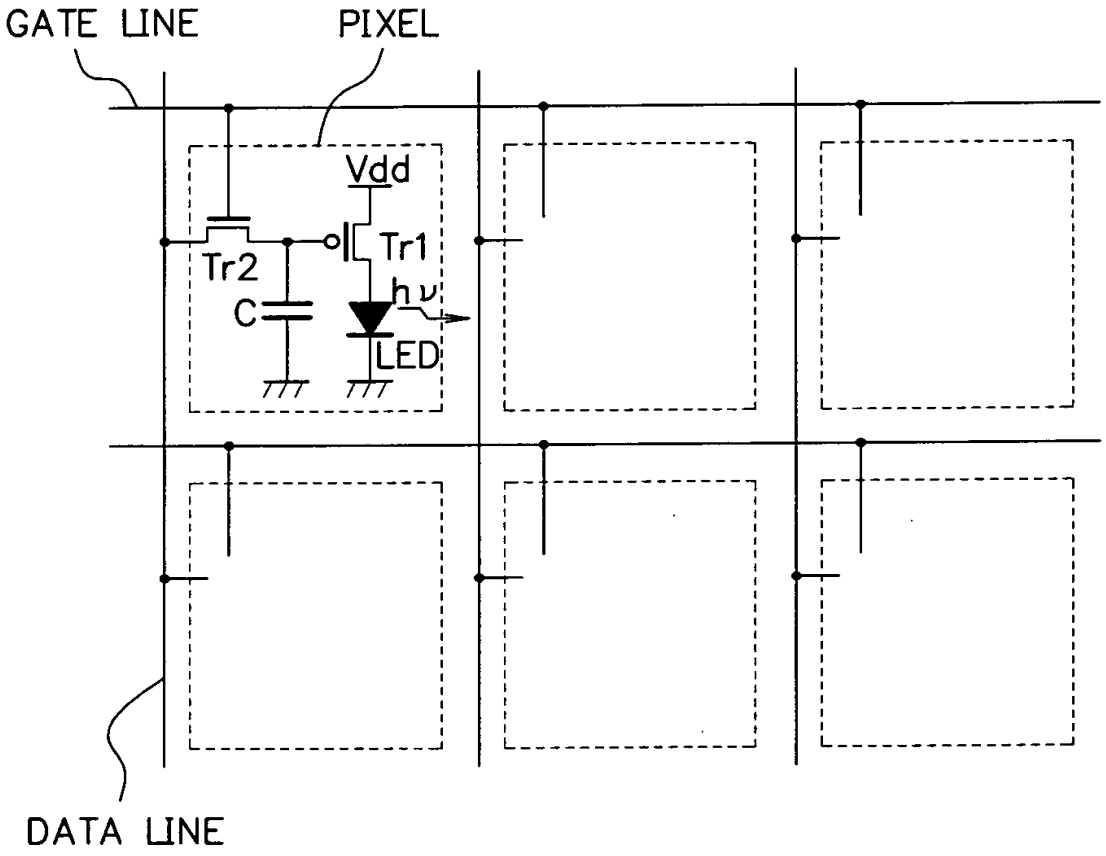


FIG. 10



F I G. 11

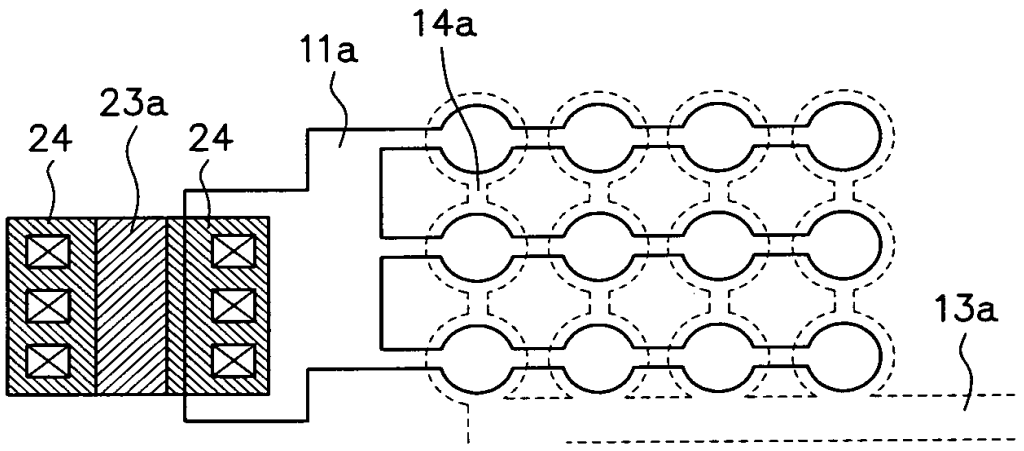
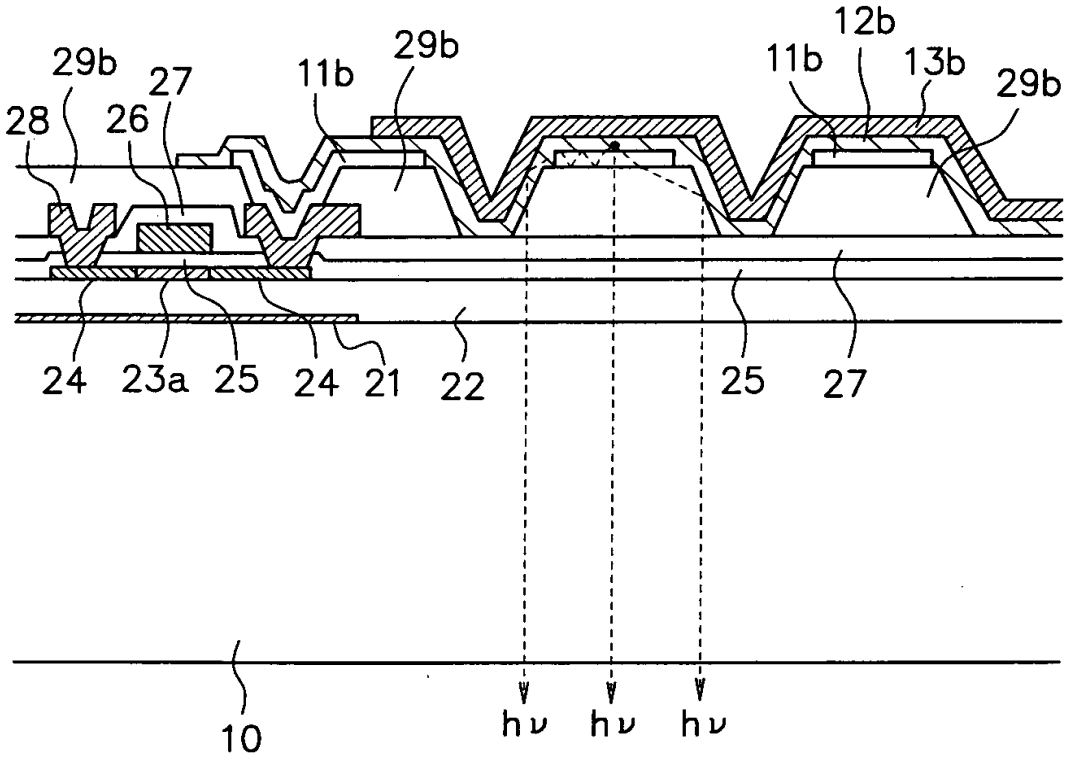


FIG. 12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25
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FIG. 13

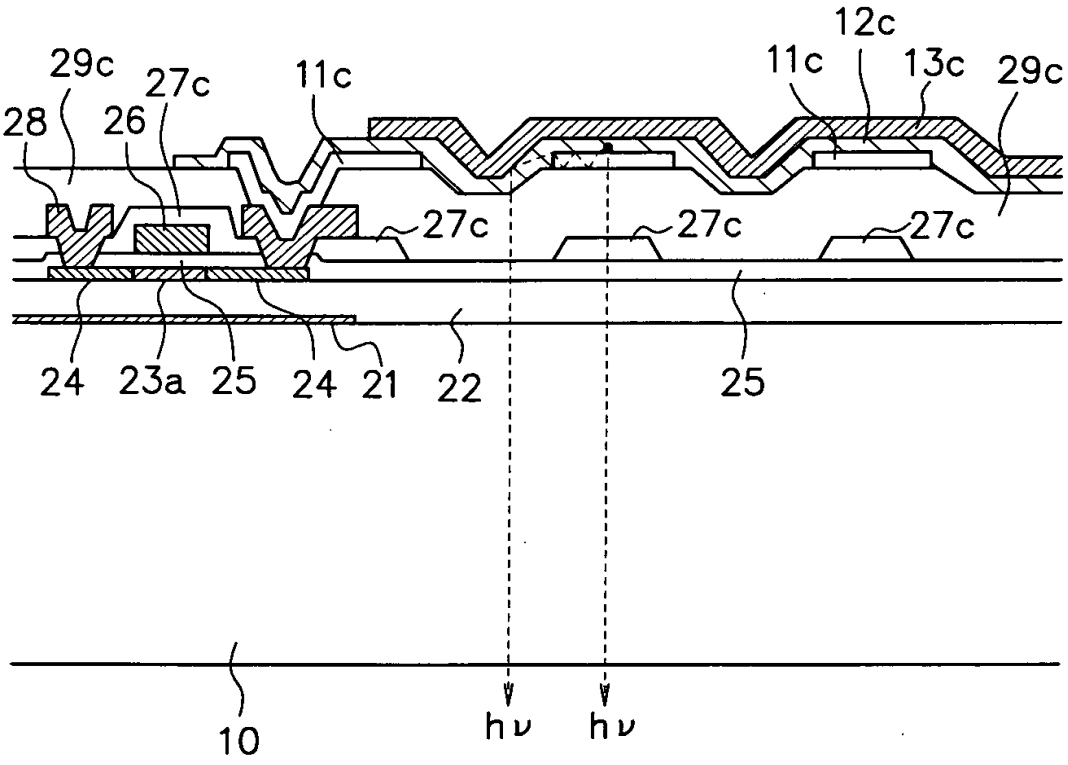
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FIG. 14

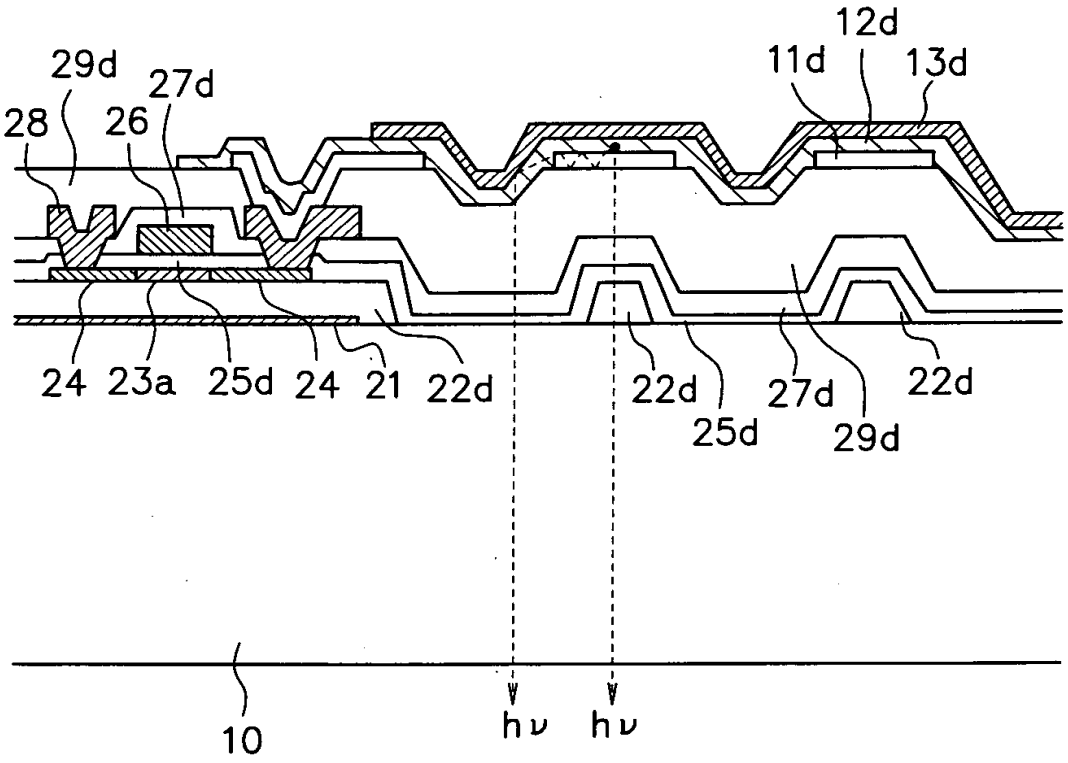
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FIG. 15

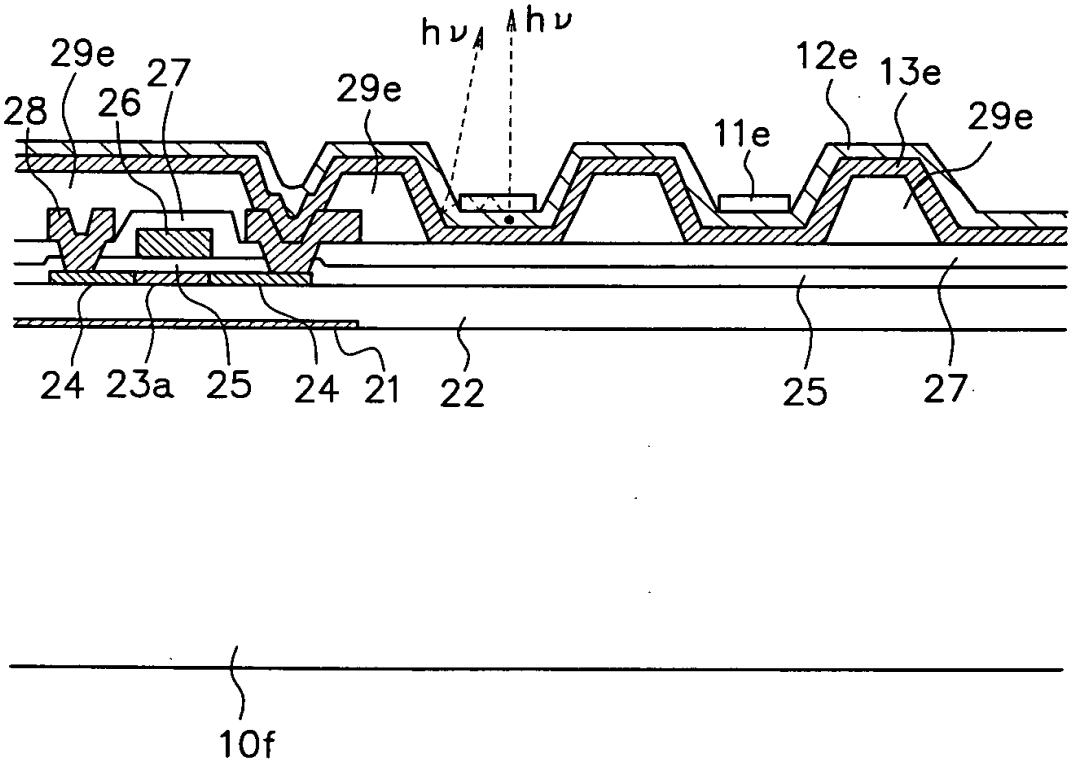

FIG. 16